

# HZL6.2Z4

## Silicon Planar Zener Diode for Surge Absorb

REJ03G0409-0100

Rev.1.00

Oct 01, 2004

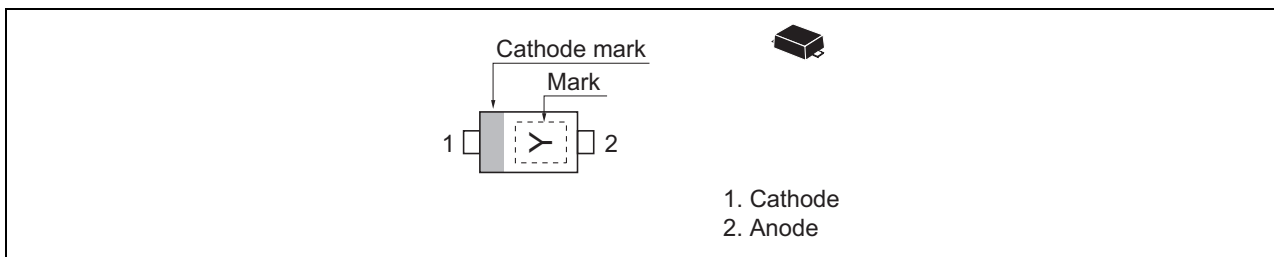
### Features

- Low capacitance ( $C = 4.0 \text{ pF max}$ ) and can protect ESD of signal line.
- Extremely small Flat Package (EFP) is suitable for surface mount design.

### Ordering Information

| Type No. | Laser Mark | Package Code |
|----------|------------|--------------|
| HZL6.2Z4 | Y          | EFP          |

### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

| Item                 | Symbol | Value       | Unit |
|----------------------|--------|-------------|------|
| Power dissipation    | Pd *   | 100         | mW   |
| Junction temperature | Tj     | 150         | °C   |
| Storage temperature  | Tstg   | -55 to +150 | °C   |

Note: See Fig.2.

## Electrical Characteristics

(Ta = 25°C)

| Item               | Symbol | Min  | Typ | Max  | Unit | Test Condition   |
|--------------------|--------|------|-----|------|------|--|
| Zener voltage      | Vz     | 5.90 | —   | 6.50 | V    | Iz = 5 mA, 40 ms pulse   |
| Reverse current    | IR     | —    | —   | 3    | μA   | VR = 5.5 V   |
| Capacitance        | C      | —    | —   | 4.0  | pF   | VR = 0 V, f = 1 MHz  |
| Dynamic resistance | rd     | —    | —   | 60   | Ω    | Iz = 5 mA  |
| ESD-Capability *1  | —      | 8    | —   | —    | kV   | C = 150 pF, R = 330 Ω, Both Forward and reverse direction 10 pulse |

Notes: 1. Failure criterion ; IR &gt; 3 μA at VR = 5.5 V.

2. Please do not use the soldering iron due to avoid high stress to the EFP package.

3. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

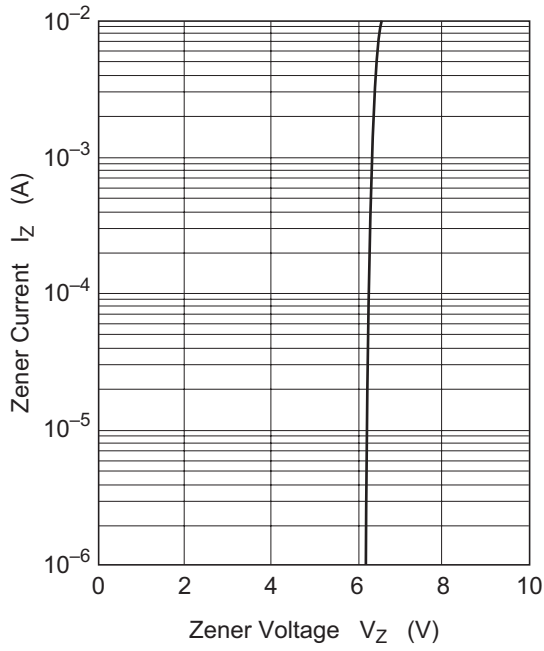


Fig.1 Zener current vs. Zener voltage

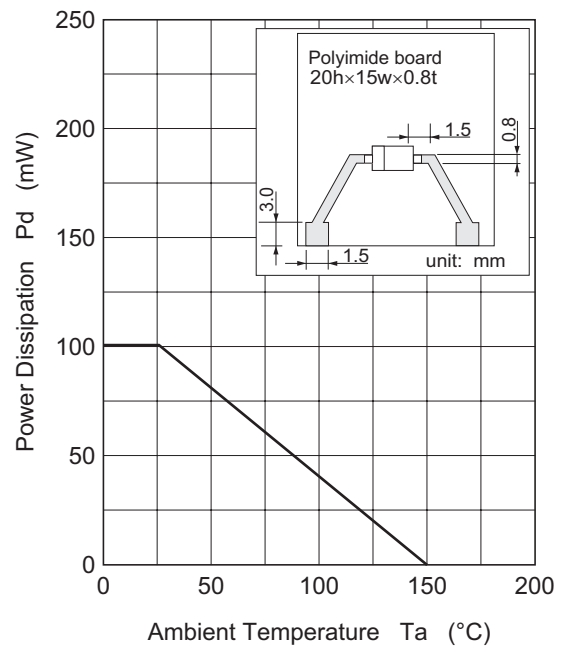


Fig.2 Power Dissipation vs. Ambient Temperature

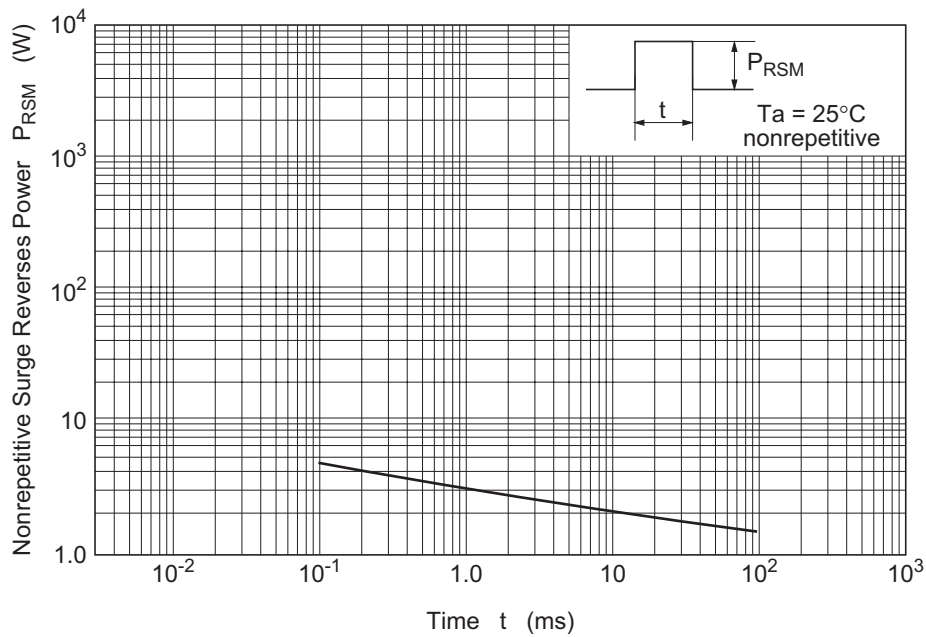
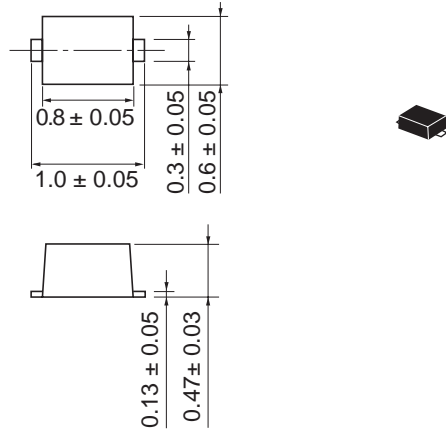


Fig.3 Surge Reverse Power Ratings

Package Dimensions

As of January, 2003  
Unit: mm



|                        |          |
|------------------------|----------|
| Package Code           | EFP      |
| JEDEC                  | —        |
| JEITA                  | —        |
| Mass (reference value) | 0.0007 g |

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